

Title (en)
METHOD FOR GLUING FLEXIBLE CIRCUIT BOARDS TO POLYMER MATERIALS FOR PARTIAL OR COMPLETE STIFFENING

Title (de)
VERFAHREN ZUR VERKLEBUNG VON FLEXIBLEN LEITERPLATTEN MIT POLYMERMATERIALIEN ZUR PARTIELLEN ODER VOLLSTÄNDIGEN VERSTEIFUNG

Title (fr)
PROCÉDÉ DE COLLAGE DE CARTES DE CIRCUITS IMPRIMÉS FLEXIBLES AVEC DES MATÉRIAUX POLYMÈRES EN VUE D'OBTENIR UNE RIGIDIFICATION PARTIELLE OU COMPLÈTE

Publication
EP 2238815 A2 20101013 (DE)

Application
EP 09705439 A 20090121

Priority
• EP 2009050666 W 20090121
• DE 102008006390 A 20080128

Abstract (en)
[origin: WO2009095347A2] A method for producing circuit boards, comprising a process for modifying a flexible circuit board, in particular for the stabilization thereof, characterized by at least the following method steps: a) providing a planar formation ("reinforcement plate") having lower flexibility than that of the flexible circuit board, b) hot laminating an adhesive film, which can be activated by heat, on the reinforcement plate, c) placing the laminate made of adhesive film and reinforcement plate with the adhesive film side on the flexible circuit board, d) introducing the component made of reinforcement plate, adhesive film, and flexible circuit board into a partial vacuum atmosphere, e) hot laminating the component with application of pressure and heat.

IPC 8 full level
H05K 3/00 (2006.01)

CPC (source: EP US)
B32B 37/10 (2013.01 - EP US); **H05K 3/0061** (2013.01 - EP US); **H05K 3/0064** (2013.01 - EP US); **B32B 2309/68** (2013.01 - EP US); **B32B 2457/08** (2013.01 - EP US); **H05K 1/0393** (2013.01 - EP US); **H05K 3/386** (2013.01 - EP US); **H05K 2203/068** (2013.01 - EP US); **H05K 2203/085** (2013.01 - EP US)

Citation (search report)
See references of WO 2009095347A2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA RS

DOCDB simple family (publication)
DE 102008006390 A1 20090730; CN 101990790 A 20110323; EP 2238815 A2 20101013; JP 2011527095 A 20111020; KR 20100111734 A 20101015; TW 200942109 A 20091001; US 2011094676 A1 20110428; WO 2009095347 A2 20090806; WO 2009095347 A3 20091029

DOCDB simple family (application)
DE 102008006390 A 20080128; CN 200980109258 A 20090121; EP 09705439 A 20090121; EP 2009050666 W 20090121; JP 2010543488 A 20090121; KR 20107019158 A 20090121; TW 98100893 A 20090112; US 86463709 A 20090121